US00D608308S

(12) **United States Design Patent**
Hsieh

(10) **Patent No.:** **US D608,308 S**
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(54) **LIGHT EMITTING DIODE PACKAGE**

(75) Inventor: **Chung-Chuan Hsieh**, Taipei (TW)

(73) Assignee: **Everlight Electronics Co., Ltd**, Taipei (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/331,121**

(22) Filed: **Jan. 21, 2009**

(30) **Foreign Application Priority Data**

Dec. 12, 2008 (TW) 97307053

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/180**
(58) **Field of Classification Search** D13/180; D26/2; 257/79, 80, 81, 88, 89, 95, 98, 99, 257/100; 313/483, 498, 500; 362/555, 800
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown.

DESCRIPTION

FIG. **1** is a perspective view of a light emitting diode package showing the new design.

FIG. **2** is a front view thereof.

FIG. **3** is a rear view thereof.

FIG. **4** is a left side view thereof.

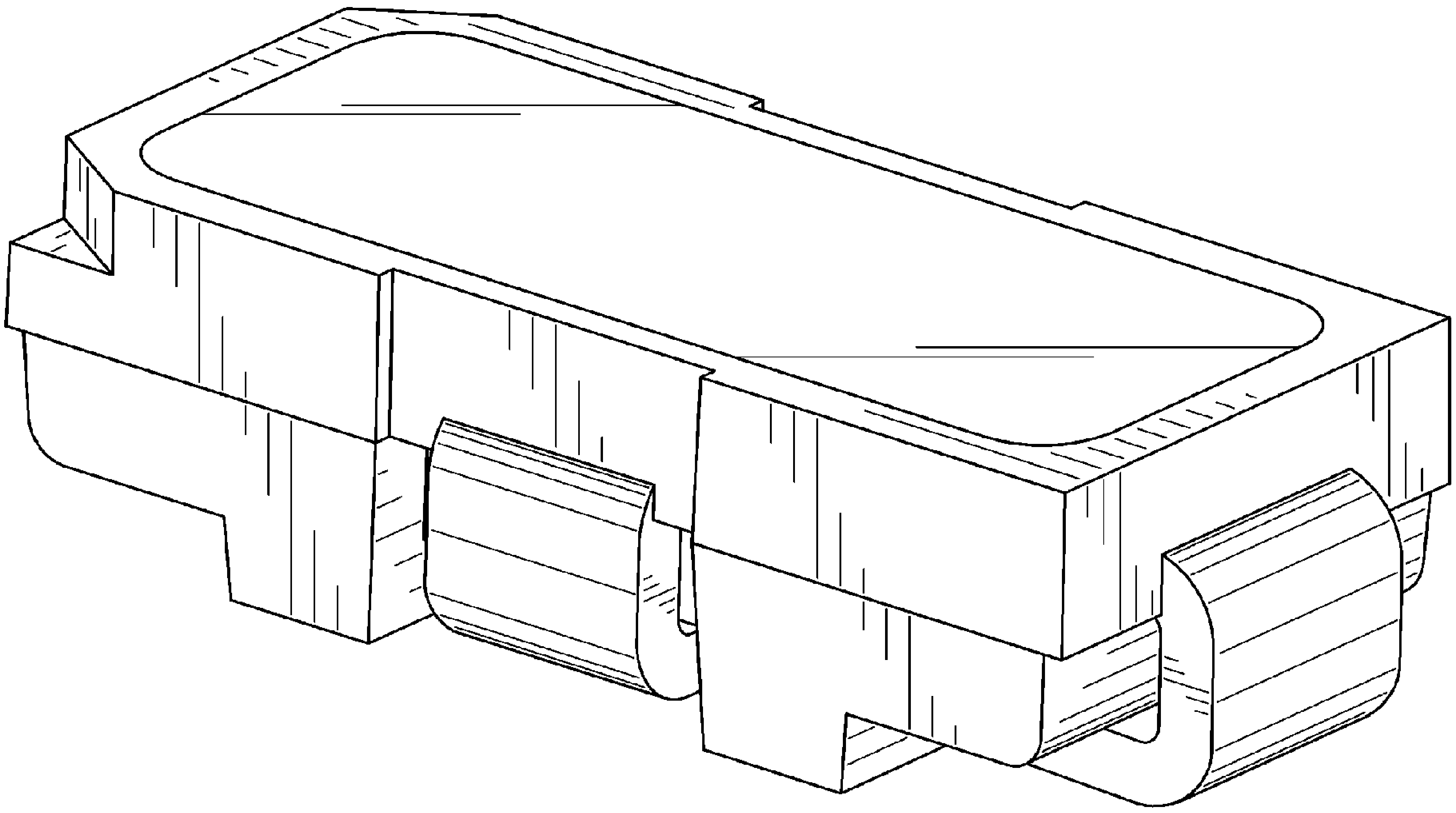
FIG. **5** is a right side view thereof.

FIG. **6** is a top view thereof.

FIG. **7** is a bottom view thereof; and,

FIG. **8** is another perspective view thereof.

1 Claim, 7 Drawing Sheets



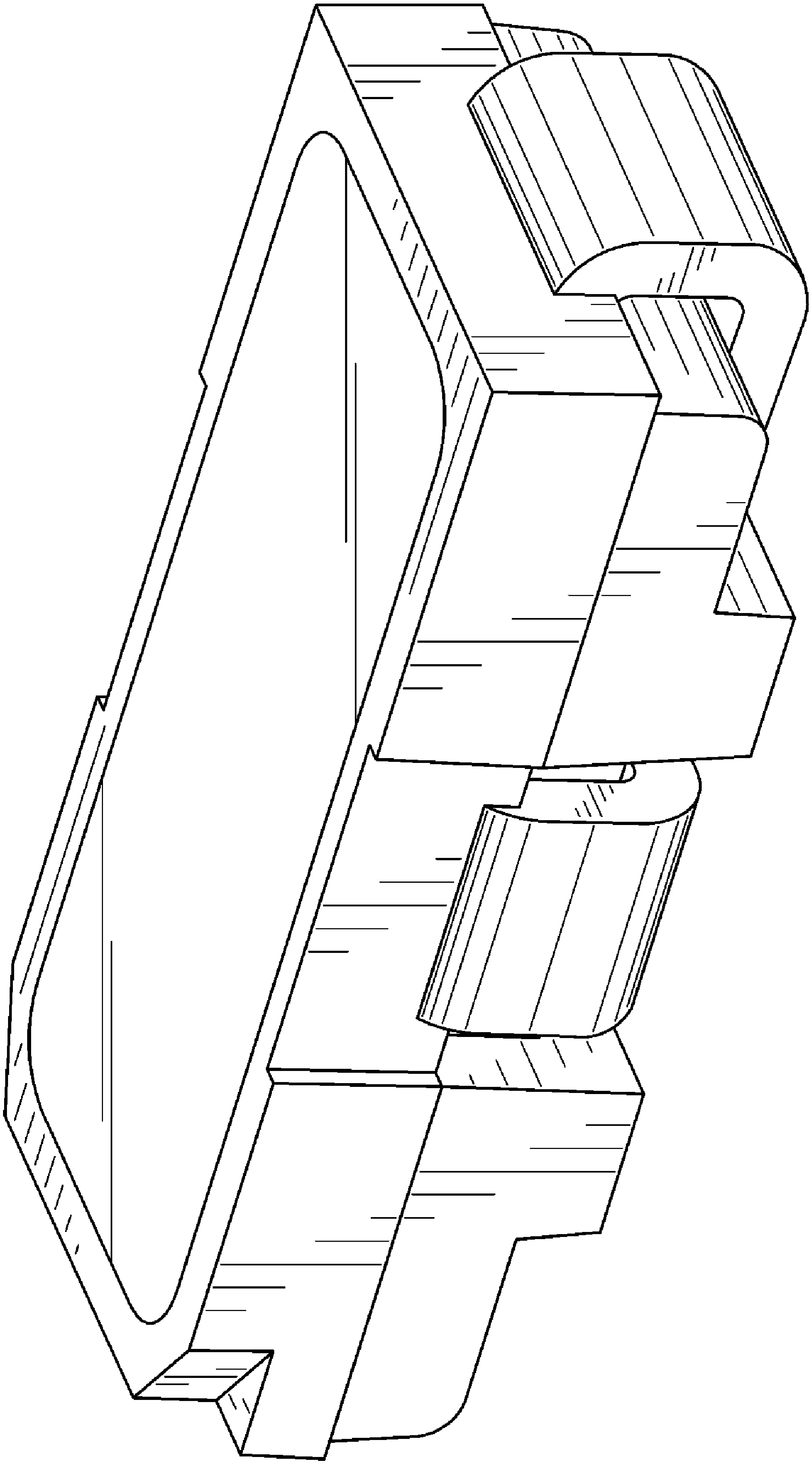


FIG. 1

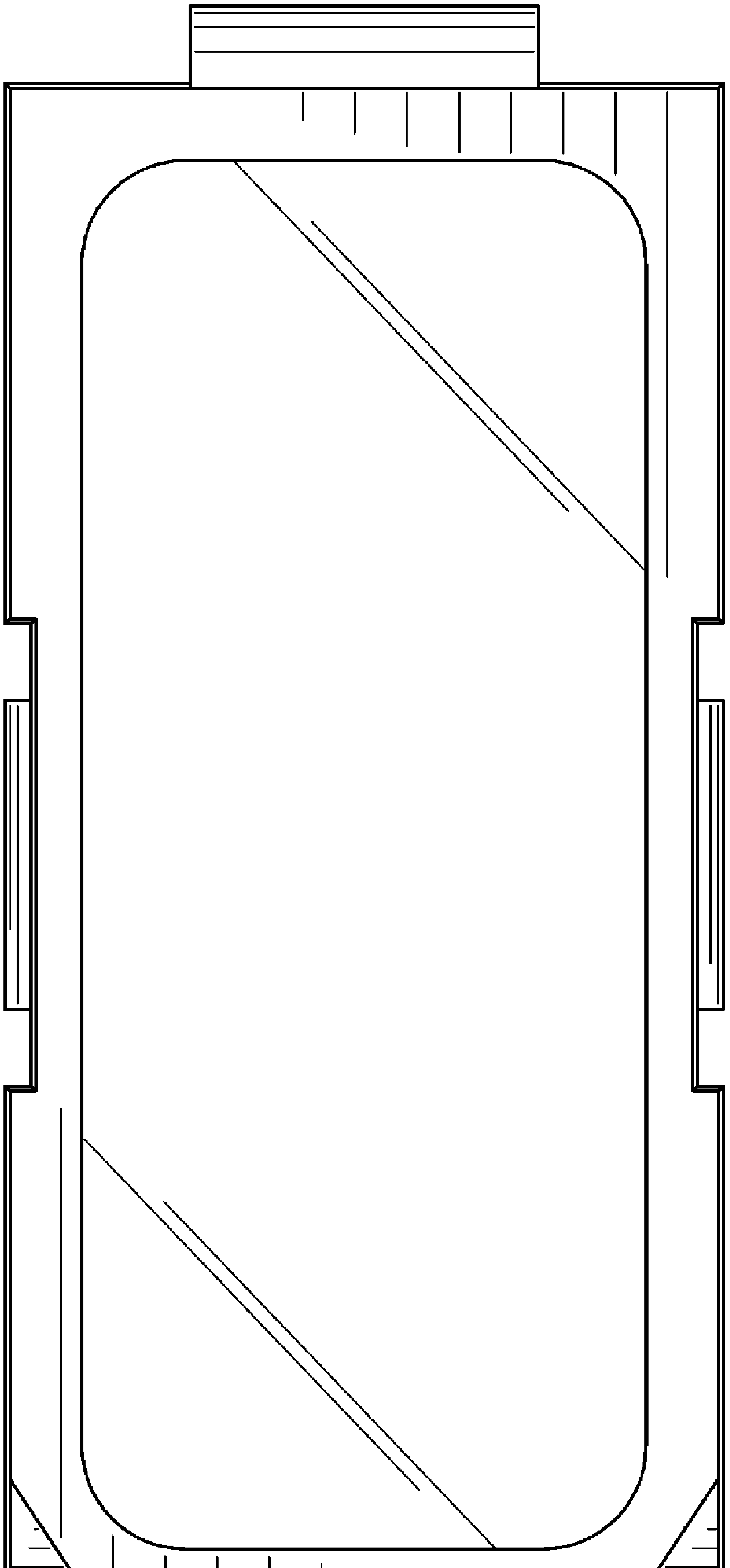


FIG. 2

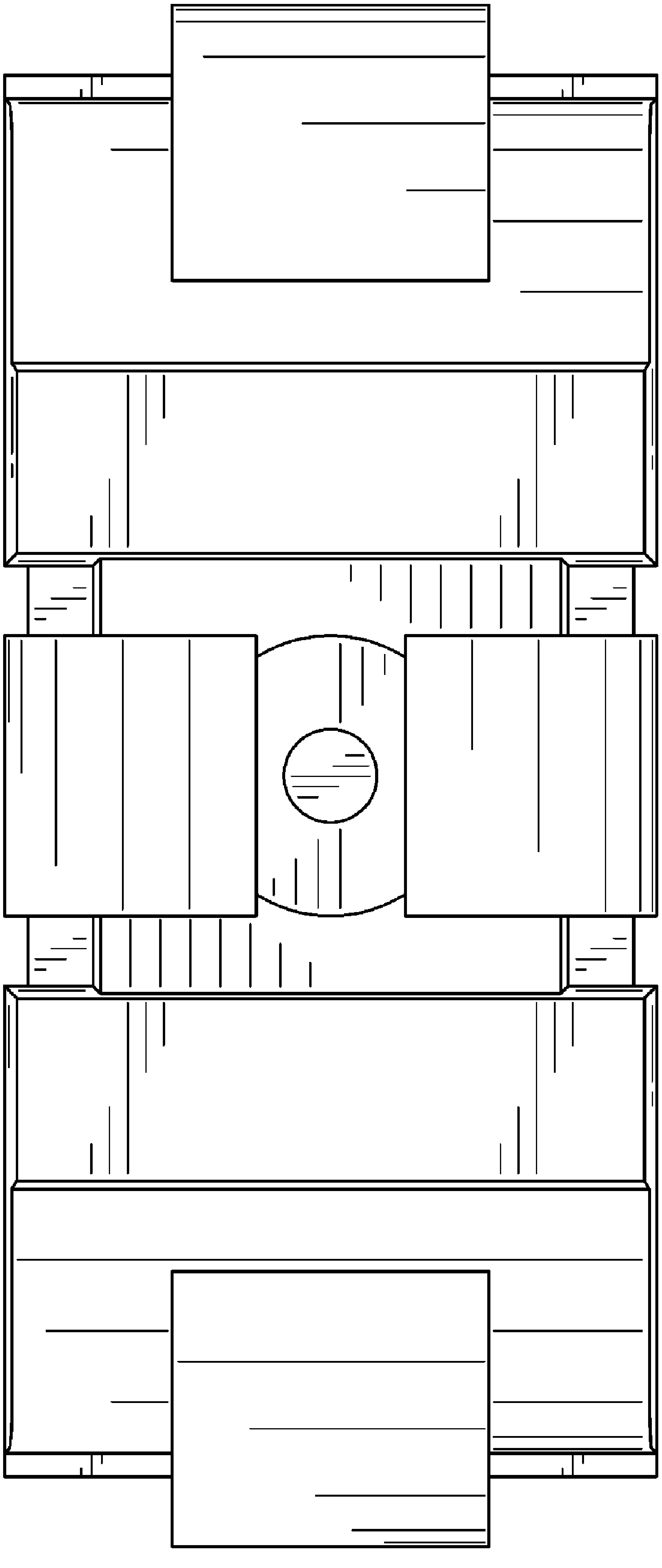


FIG. 3

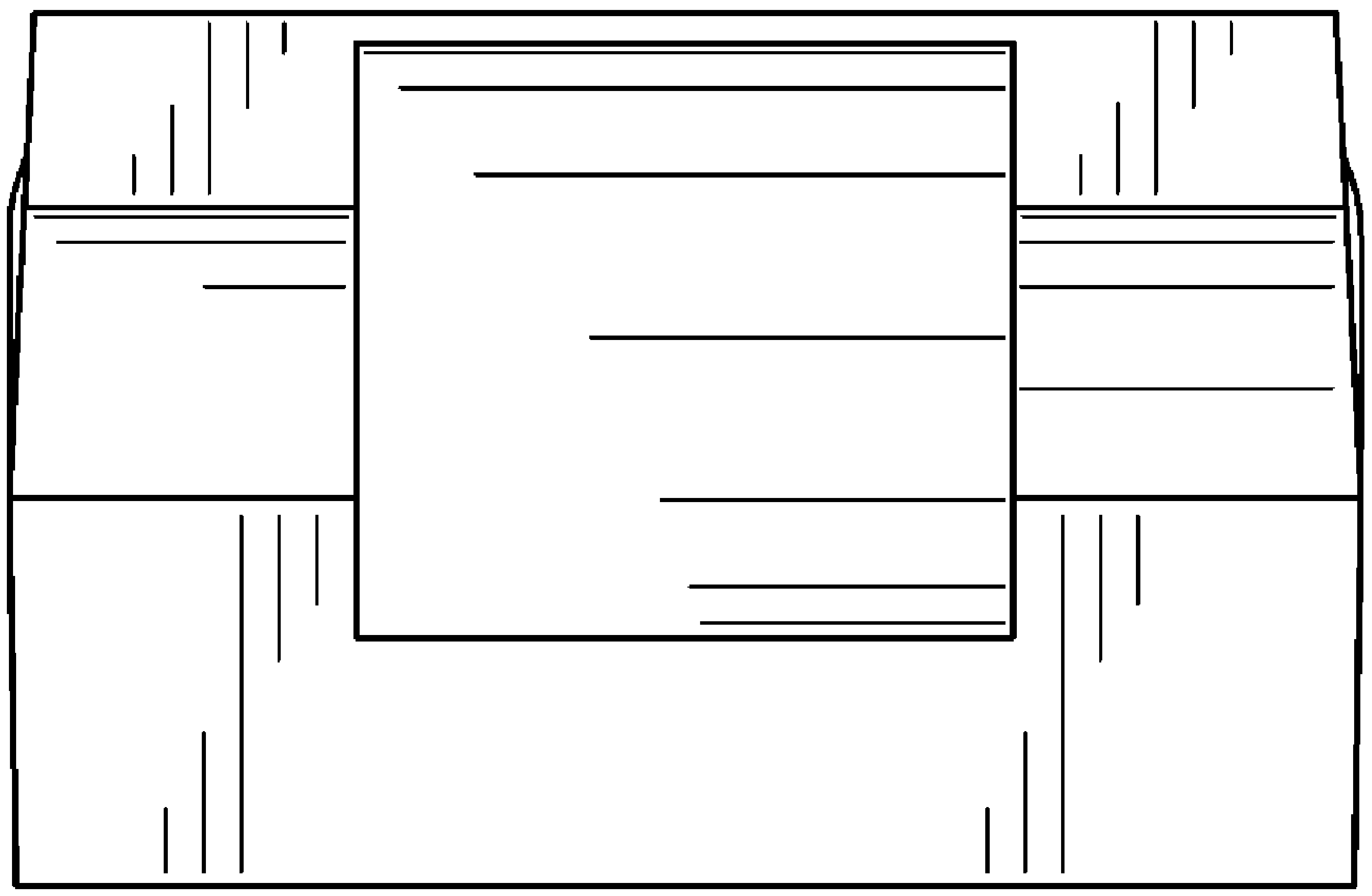


FIG. 5

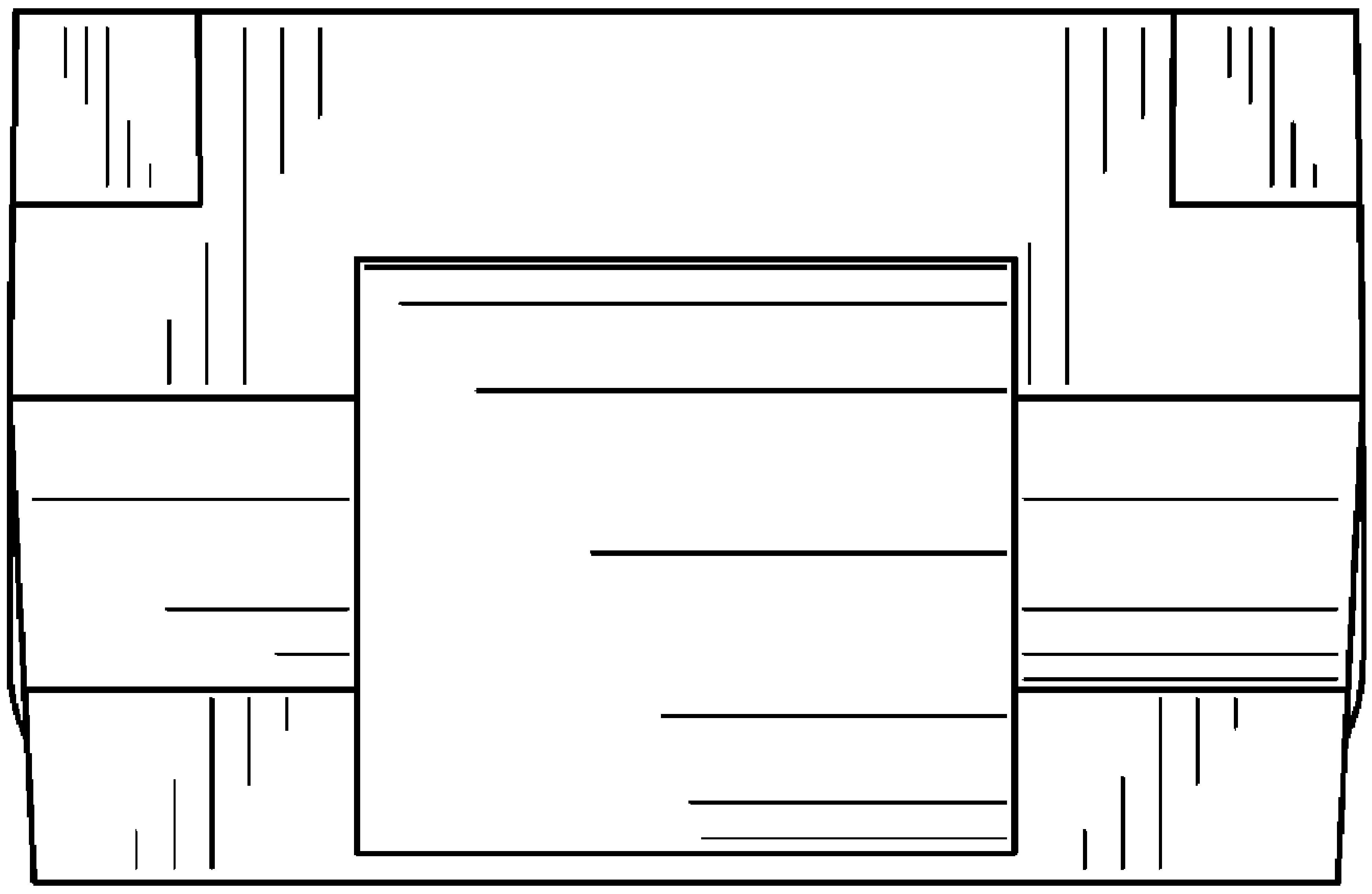


FIG. 4

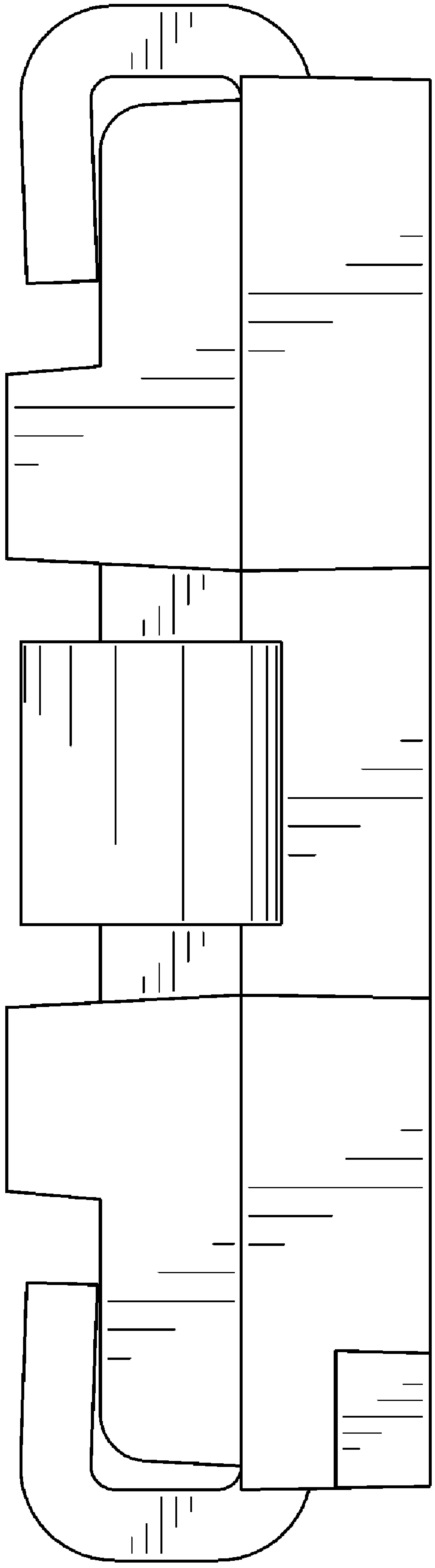


FIG. 6

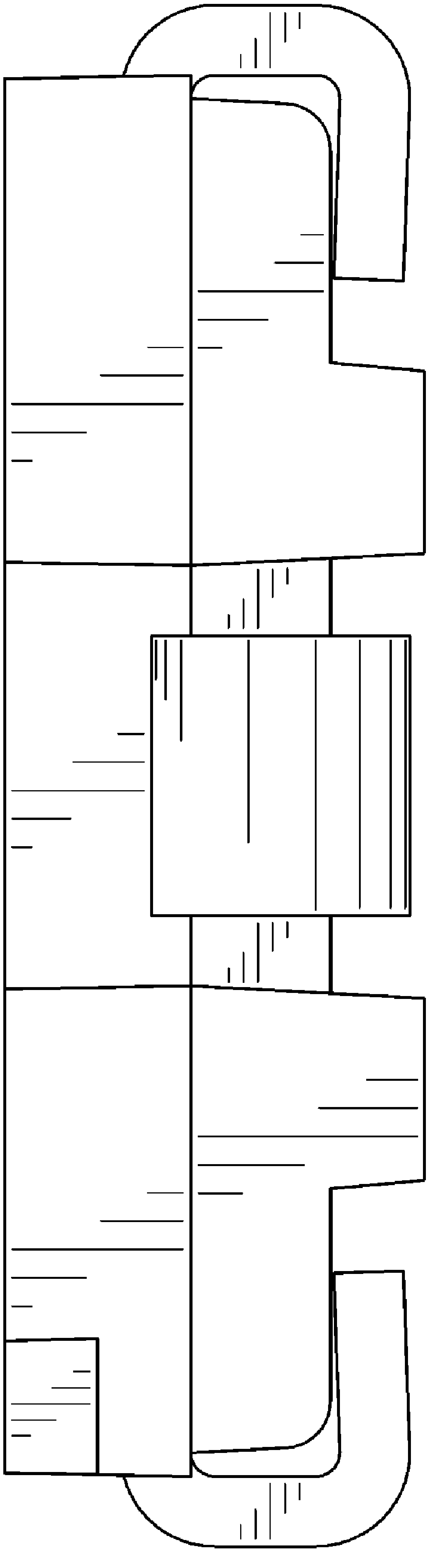


FIG. 7

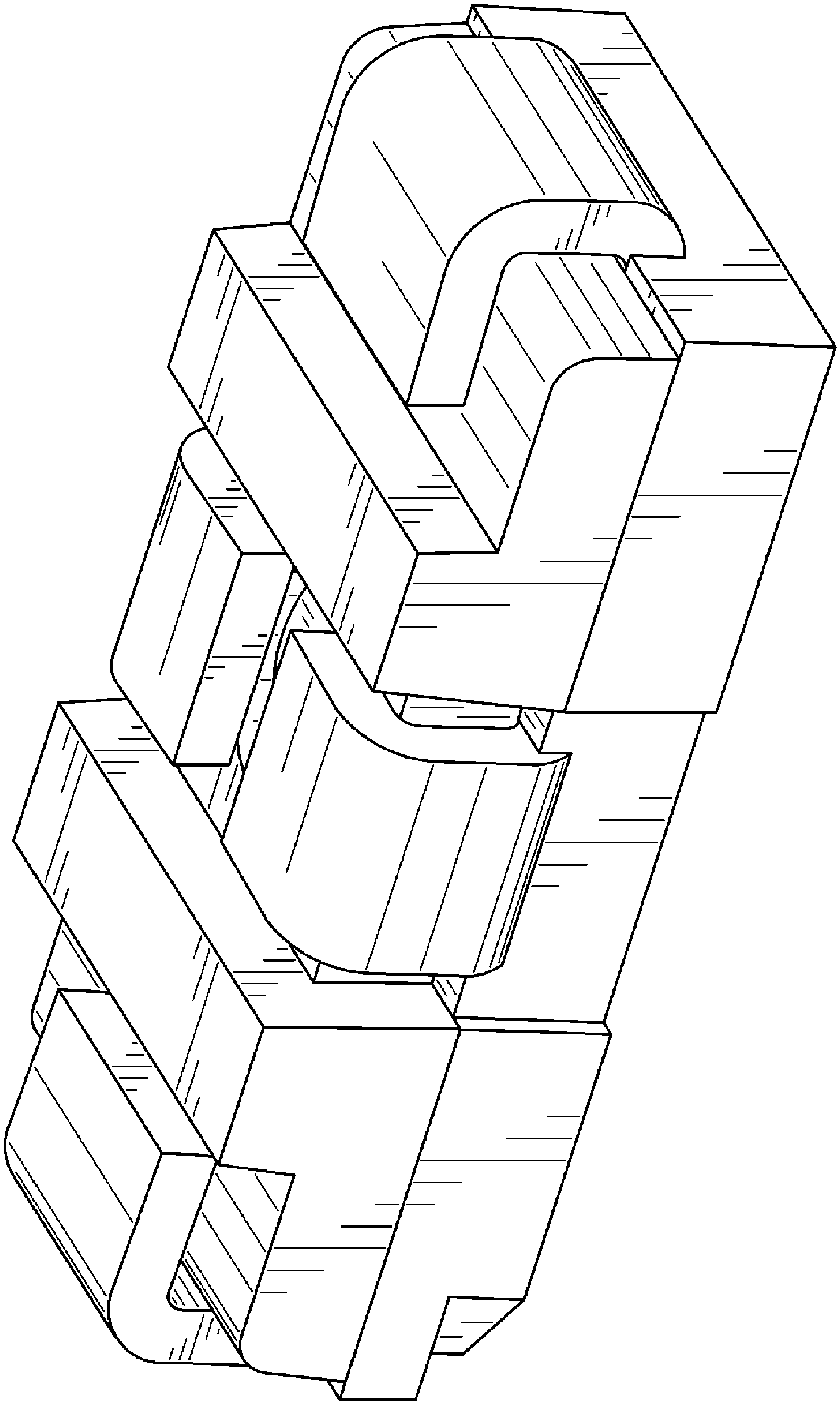


FIG. 8